



BITNG LAB UPDATE

Carl Demolder

Date 6/07/2021

Progress from last week

- Shriner's project
 - Strain sensor manufacturing
 - PCB redesign
 - Waiting for workday confirmation
- LP ECG
 - Waiting for workday confirmation
- Chip socket programmer
 - Assembly and debugging complete

SHRINER'S PROJECT

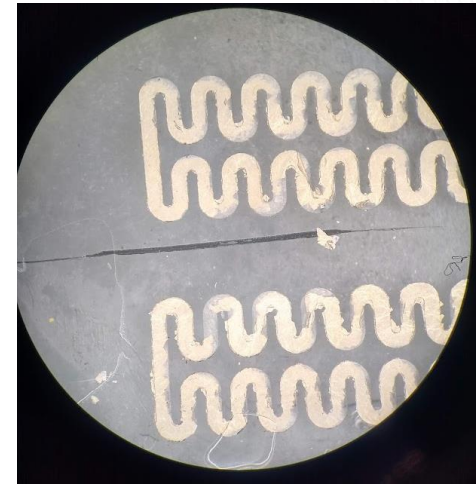
Strain sensor

Problem:

- Flakey AgNW
- Clumps and sticks together
- Disconnection in AgNW
- Bonds to the PI stencil

Proposed solution:

- Plasma treat PDMS
 - Result: No obvious benefit
- Oven instead of hot plate
 - Result: Lower temperature improves surface quality ~ 50 C
- PI film with single side adhesive instead of two-sided adhesive
 - Result: Better removal of stencil from PDMS base material



Cracks in AgNW



$W = 0.5 \text{ mm}$

Strain sensor

Observation:

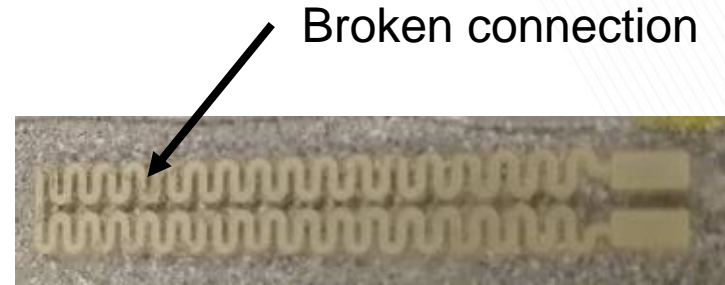
- Rounded pattern has a higher likely hood of removing AgNW from PDMS

Proposed solution:

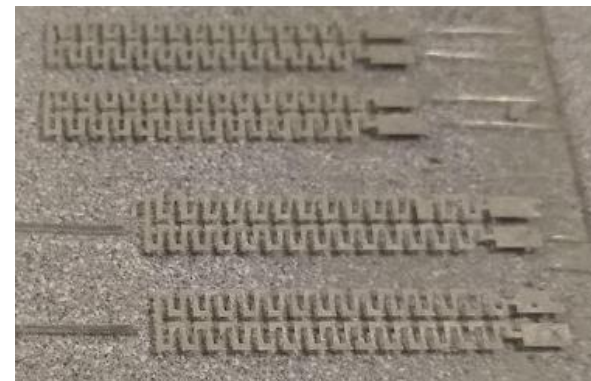
- Square serpentines instead of rounded serpentines
 - Rational: Square/sharp pattern will cause shear force to split AgNW

Results:

- No obvious benefit



Rounded serpentine pattern



Square serpentine pattern

Strain sensor

Problem:

- Serpentine pattern increases the likelihood of flakes and cracks in AgNW
- Most academic papers of an AgNW strain sensor have a width > 3 mm

Solution:

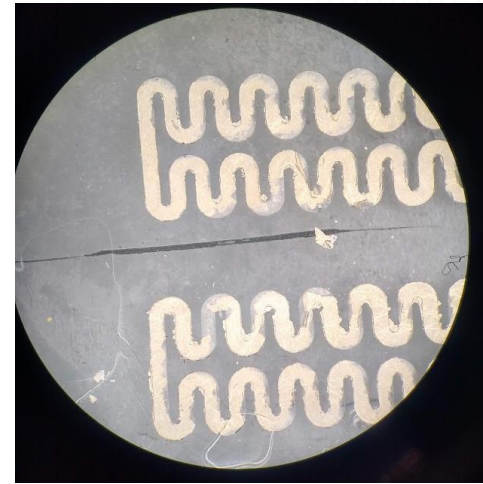
- Straight line AgNW

Result:

- Works effectively
- Manufacturing yield is about 50%
- Width = 0.5 mm

Takeaway:

- Thicker width increases likelihood of success



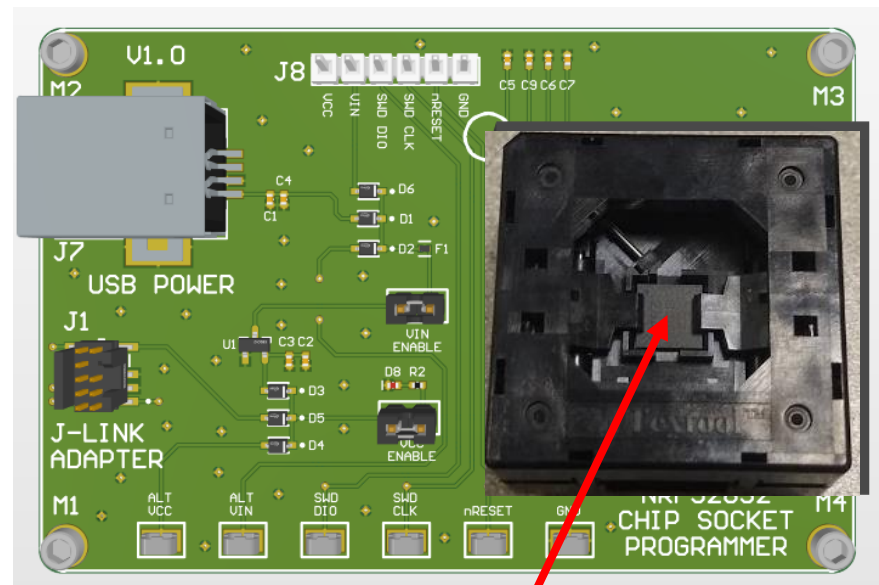
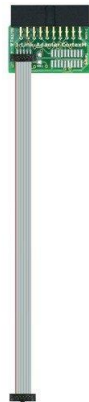
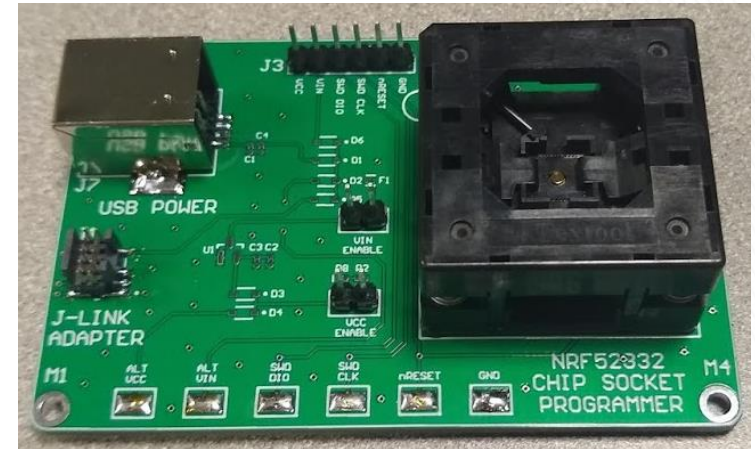
Cracks in AgNW



Strain Sensor

Chip Socket Programmer

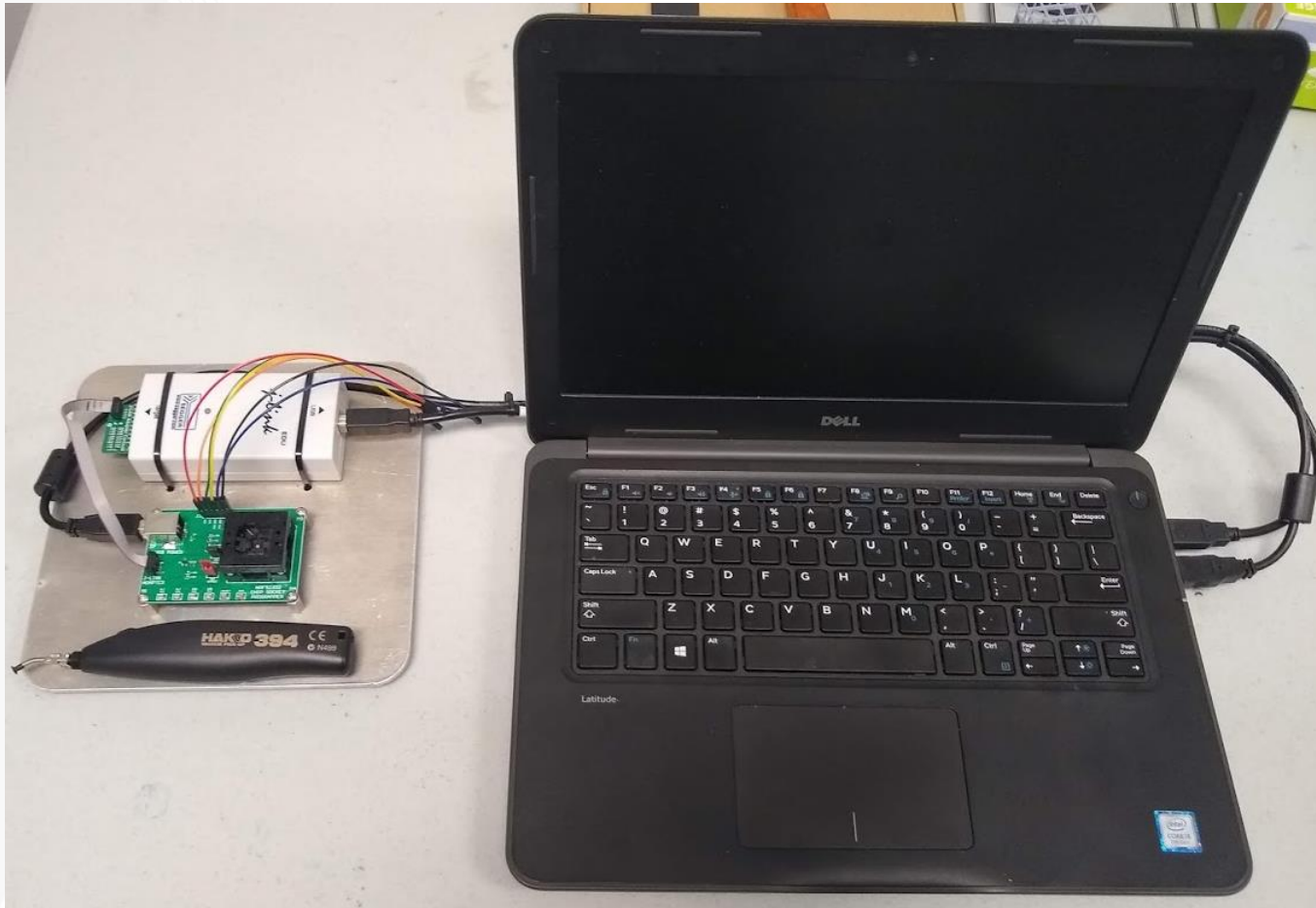
- PCB: DELIVERED
- COMPONENTS: DELIVERED
- Assembly: COMPLETE



NRF52

Chip Socket Programmer

- Instructional Video: To-Do



PATH FORWARD

Path forward (6/07/21 – 6/14/21)

- Shriner's Project:
 - Sensor fabrication:
 - Strain sensor
 - Laser cutter booked: 6/12
 - Pressure sensor
 - Sensor characterization:
 - Strain sensor
 - Pressure sensor
 - Temperature sensor

APPENDIX